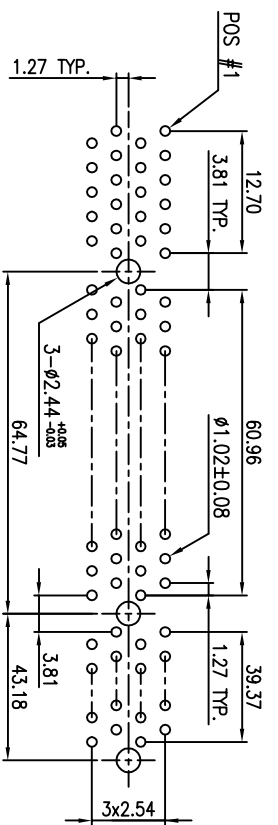
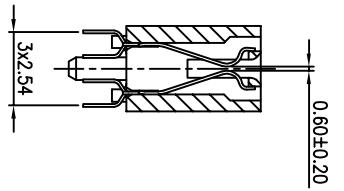
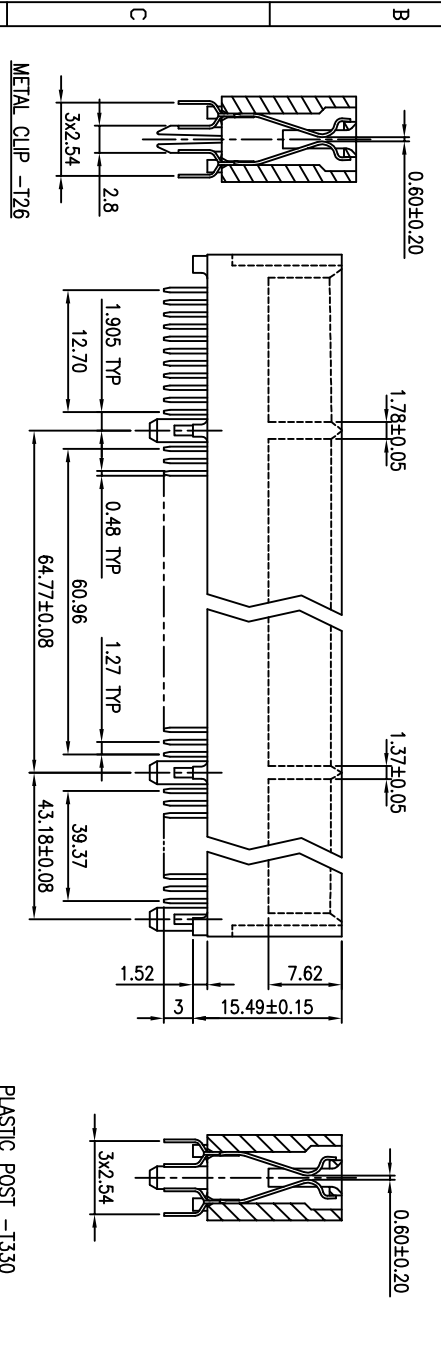
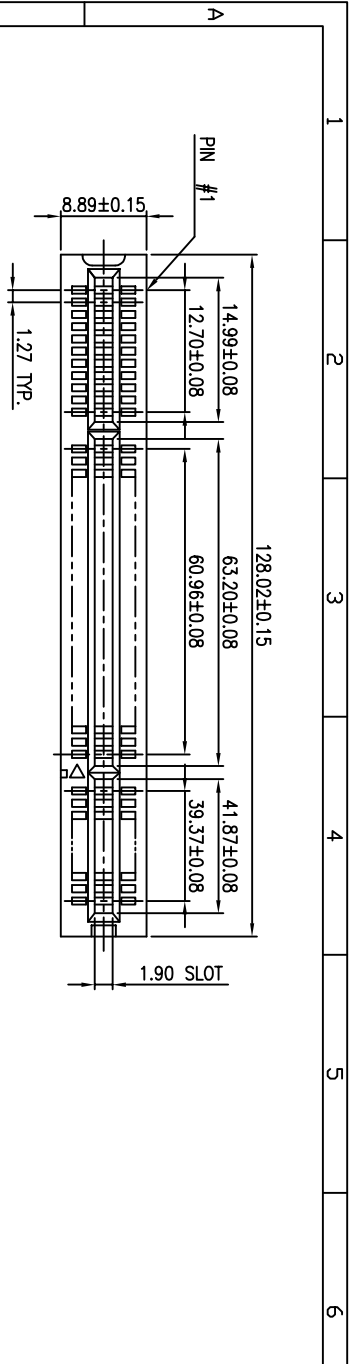


REV	DESCRIPTION	BY	DATE
A	Added position 1 indicators	BC	06-03-03



RECOMMENDED PCB LAYOUT

X ±	X* ± 1*	FINISH
X ± 0.10	X* ± 0.5*	
XX ± 0.05	XX* ±	QTY
XXX ±	XXX* ±	

UNITS	MM	NAME (INTENDED USE)	SULLINS ELECTRONICS CORP
MAT'L		PART NO. (INTENDED USE)	TITLE: 64 BIT PCI CARDEGE, 3.3V
APPD:			PART NO. TRXB092DKHN-T330/T26
CHKD:			SCALE NONE
DRWN: N.Boone	9/23/97		SHEET 1 OF 1
			REV A

**MATERIAL**  
 INSULATOR: GLASS-REINFORCED THERMOPLASTIC,  
 U194V-0 RATED.  
 CONTACT: COPPER ALLOY.  
 PLATING: MATING AREA- GOLD,  
 SOLDER AREA- TIN/LEAD.

**ELECTRICAL**  
 VOLTAGE RATING: 250 VAC RMS.  
 CURRENT RATING: 3 AMP.  
 INSULATION RESISTANCE: 1,000 MEGOHMS MIN.  
 CONTACT RESISTANCE: 30 MILLIOHMS MAX.

**MECHANICAL**  
 CONTACT RETENTION: 460 GRAMS MIN PER CONTACT.  
 INSERTION FORCE: 230 GRAMS MAX PER CONTACT PAR.  
 WITHDRAWAL FORCE: 15 GRAMS MIN PER CONTACT PAR.

**ENVIRONMENTAL**  
 TEMPERATURE RANGE: -55° TO +85°.  
 NO PART MARKINGS

**GOLD PLATING**  
 REPLACE "\*" IN THE PART NUMBER:  
 W = SELECTIVE GOLD FLASH  
 Z = SELECTIVE 100μ" GOLD  
 X = SELECTIVE 30μ" GOLD